



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

John W. ANDREWS et al.

Serial No.: 09/883,981

Group Art Unit: 2813

Filed: June 20, 2001

Examiner: David S. Blum

For: LOW COST SHALLOW TRENCH ISOLATION USING NON-CONFORMAL  
DIELECTRIC MATERIAL

Honorable Commissioner of Patents  
Washington, D.C. 20231

**STATEMENT OF SUBSTANCE OF INTERVIEW**

Sir:

Applicant provides herewith his Statement of Substance of the telephone interview which was conducted between the Examiner and Applicant's undersigned counsel on April 23, 2004.

Applicant states that during the interview, Applicant pointed out to the Examiner that the claimed invention was not taught or suggested by the cited references nor by any combination of the cited references. Specifically, Applicant pointed out that the references do not teach or suggest a semiconductor substrate having a trench region and a non-trench region, in which a thickness of a single layer of HDP oxide includes an as-deposited thickness.

Applicant's undersigned counsel also pointed out that the claims were clear and not indefinite and did not contradict the Specification, and that Amendment filed on March 16, 2004 did not raise new issues.

Respectfully Submitted,

Phillip E. Miller  
Reg. No. 46,060

Date: 5/10/04

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